

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A pattern forming method for forming a linear film pattern by arranging droplets of a liquid material on a substrate, the method comprising:

a first step of arranging the droplets₁ whose width is smaller than that of the film pattern₁ on the substrate and forming a central part of the film pattern by depositing a plurality of first droplets spaced apart from each other on the substrate and depositing second droplets in spaces between the first droplets;

a second step of arranging the droplets₁ whose width is smaller than that of the film pattern₁ on the substrate and forming one side with respect to the formed central part by depositing a plurality of third droplets spaced apart from each other on the substrate and depositing fourth droplets in spaces between the third droplets; and

a third step of arranging the droplets₁ whose width is smaller than that of the film pattern₁ on the substrate and forming the other side with respect to the formed central part by depositing a plurality of fifth droplets spaced apart from each other on the substrate and depositing sixth droplets in spaces between the fifth droplets.

2. (Original) The pattern forming method according to Claim 1,
wherein the droplets are arranged on the substrate so that the droplets overlap with at least a part of the central part formed on the substrate to form the sides.

3. (Cancelled)

4. (Original) The pattern forming method according to Claim 1,

wherein arrangement conditions of the droplets in the first, second, and third steps are set differently.

5. (Original) The pattern forming method according to Claim 4, wherein the arrangement intervals of the droplets on the substrate in the first, second, and third steps are set to different values.

6. (Original) The pattern forming method according to Claim 4, wherein the volumes of the droplets in the first, second, and third steps are set to different values.

7. (Original) The pattern forming method according to Claim 1, further comprising a surface treatment step of adjusting a lyophobic property of the surface of the substrate before arranging the droplets on the substrate.

8. (Original) The pattern forming method according to Claim 1, wherein the liquid material comprises conductive particles.

9. (Cancelled)

10. (Currently Amended) A method of manufacturing a device having a linear wiring pattern comprising a material arrangement step of arranging droplets of a liquid material on a substrate,

wherein the material arrangement step comprises:

a first step of arranging the droplets₁ whose width is smaller than that of the wiring pattern₁ on the substrate and forming a central part of the wiring pattern by

depositing a plurality of first droplets spaced apart from each other on the substrate and depositing second droplets in spaces between the first droplets;

a second step of arranging the droplets₁ whose width is smaller than that of the wiring pattern₁ on the substrate and forming one side with respect to the formed central part by depositing a plurality of third droplets spaced apart from each other on the substrate and depositing fourth droplets in spaces between the third droplets; and

a third step of arranging the droplets₁ whose width is smaller than that of the wiring pattern₁ on the substrate and forming the other side with respect to the formed central part by depositing a fifth plurality of droplets spaced apart from each other on the substrate and depositing sixth droplets in spaces between the fifth droplets.

11. – 13. (Cancelled)

14. (Currently Amended) A pattern forming method for forming a film pattern by arranging droplets of a liquid material on a substrate, the method comprising:

a first step of discharging a ~~first~~ plurality of the linearly spaced apart first droplets in an elongated central part of the film pattern on the substrate and thereafter discharging a set of linearly spaced apart second droplets on the substrate, the second droplets filling in gaps between the first droplets;

a second step of discharging a ~~second~~ plurality of the linearly spaced apart third droplets along a first side of the formed central part, the third ~~second~~ plurality of the droplets partially overlapping the formed central part and thereafter discharging a set of linearly spaced apart fourth droplets on the substrate, the fourth droplets filling in gaps between the third droplets; and

a third step of discharging a ~~third~~ plurality of the linearly spaced apart fifth droplets along a second side of the formed central part, the fifth ~~third~~ plurality of the

droplets partially overlapping the formed central part and thereafter discharging a set of linearly spaced apart sixth droplets on the substrate, the sixth droplets filling in gaps between the fifth droplets.

15. - 16. (Cancelled)

17. (Currently Amended) The pattern forming method of claim 14 [[16]]
wherein:

the third droplets partially overlap the first droplets; and
the fourth droplets partially overlap the second droplets.

18. (Cancelled)

19. (Currently Amended) The pattern forming method of claim 14 [[18]]
wherein:

the fifth droplets partially overlap the first droplets; and
the sixth droplets partially overlap the second droplets.

20. (Cancelled)